

Abstract

The present invention addresses the problem of providing: a resin material which has a novel structure and can be suitably used in a printed wiring board; and a resin composition comprising this resin material, a cured product of which has excellent base material adhesion, mechanical properties, heat resistance, lamination properties, and dielectric properties after moisture absorption. The present invention pertains to a polyimide resin that is the product of a reaction between an imidized compound (P) of a polyamic acid resin, said polyamic acid resin being a copolymer of amino compounds (A) containing an aminophenol compound (a1) having at least two amino groups per molecule, an aliphatic diamino compound (a2) having 6-36 carbon atoms and an aromatic diamino compound (a3) having no phenolic hydroxyl group and a tetrabasic acid dianhydride (B), with a compound (C) having a functional group that can react with a phenolic hydroxy group and an ethylenically unsaturated double bond group.

[No figure]